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TITLE: 480 I/O TAPE BGA, 37.5 X 37.5 PKG, 1.27 MM PITCH		DOCUMENT NO: 98ASS23799W		REV: H	
		CASE NUMBER: 1152-04		13 JUL 2005	
		STANDARD: JEDEC MO-1922 VARIATION BAT-1			

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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